

RELIABILITY REPORT  
FOR  
**MAX9203ExA**  
PLASTIC ENCAPSULATED DEVICES

May 25th, 2003

**MAXIM INTEGRATED PRODUCTS**

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Written by



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Reviewed by



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Executive Director

## Conclusion

The MAX9203 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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### I. Device Description

#### A. General

The MAX9203 high-speed, low-power, comparator features TTL logic outputs with active internal pullups. Fast propagation delay (7ns typ at 5mV overdrive) makes this device ideal for fast A/D converters and sampling circuits, line receivers, V/F converters, and many other data-discrimination, signal restoration applications.

The comparator can be powered from separate analog and digital power supplies or from a single combined supply voltage. The analog input common-mode range includes the negative rail, allowing ground sensing when powered from a single supply. The MAX9203 consumes only 9mW per comparator when powered from a +5V supply.

The MAX9203 features output latches with TTL compatible inputs. The comparator output states are held when the latch inputs are driven low.

#### B. Absolute Maximum Ratings

<u>Item</u>	<u>Rating</u>
Analog Supply Voltage (VCC - VEE)	+12V
Digital Supply Voltage (VDD)	+7V
Differential Input Voltage	(VEE - 0.3V) to (VCC + 0.3V)
Common Mode Input Voltage	(VEE - 0.3V) to (VCC + 0.3V)
Latch Input Voltage	-0.3V to (VDD + 0.3V)
Output Short-Circuit Duration To GND	Continuous
To VDD	1min
Operating Temperature Range	-45°C to +85°C
Junction Temperature	+150°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C
Continuous Power Dissipation (TA = +70°C)	
8-Pin SOT	727mW
8-Pin SO	471mW
Derates above +70°C	
8-Pin SOT	9.1mW/°C
8-Pin SO	5.9mW/°C

## II. Manufacturing Information

A. Description/Function:	Low Cost, 7ns, Low-Power Voltage Comparators
B. Process:	CB20
C. Number of Device Transistors:	116
D. Fabrication Location:	Oregon, USA
E. Assembly Location:	Philippines, Malaysia, or Thailand
F. Date of Initial Production:	April, 2001

## III. Packaging Information

A. Package Type:	<b>8-Lead Small Outline</b>	<b>8-Lead SOT</b>
B. Lead Frame:	Copper	Copper
C. Lead Finish:	Solder Plate	Solder Plate
D. Die Attach:	Silver-filled Epoxy	Non-Conductive Epoxy
E. Bondwire:	Gold (1.0 mil dia.)	Gold (1.0 mil dia.)
F. Mold Material:	Epoxy with silica filler	Epoxy with silica filler
G. Assembly Diagram:	# 05-1501-0227	# 05-1501-0228
H. Flammability Rating:	Class UL94-V0	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard JESD22-A112:	Level 1	Level 1

## IV. Die Information

A. Dimensions:	77 x 24 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Copper/Si
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal1: 6; Metal2: 8 microns (as drawn)
F. Minimum Metal Spacing:	Metal1: 2; Metal2: 3 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

- A. Quality Assurance Contacts: Jim Pedicord (Manager, Rel Operations)  
Bryan Preeshl (Executive Director)  
Kenneth Huening (Vice President)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4389 \times 80 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

▲  
Temperature Acceleration factor assuming an activation energy of 0.8eV

$$\lambda = 13.57 \times 10^{-9}$$

$$\lambda = 13.57 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

This low failure rate represents data collected from Maxim's reliability monitor program. In addition to routine production Burn-In, Maxim pulls a sample from every fabrication process three times per week and subjects it to an extended Burn-In prior to shipment to ensure its reliability. The reliability control level for each lot to be shipped as standard product is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Attached Burn-In Schematic (Spec. # 06-3124) shows the static Burn-In circuit. Maxim performs failure analysis on any lot that exceeds this reliability control level. Maxim also performs quarterly 1000 hour life test monitors. This data is published in the Product Reliability Report (**RR-1M**).

### B. Moisture Resistance Tests

Maxim pulls pressure pot samples from every assembly process three times per week. Each lot sample must meet an LTPD = 20 or less before shipment as standard product. Additionally, the industry standard 85°C/85%RH testing is done per generic device/package family once a quarter.

### C. E.S.D. and Latch-Up Testing

The CM81 die type has been found to have all pins able to withstand a transient pulse of  $\pm 2500\text{V}$ , per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of  $\pm 250\text{mA}$ .

**Table 1**  
Reliability Evaluation Test Results

**MAX9203ExA**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	PACKAGE	SAMPLE SIZE	NUMBER OF FAILURES
<b>Static Life Test</b> (Note 1)					
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality		80	0
<b>Moisture Testing</b> (Note 2)					
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality	SO	77	0
			SOT	77	0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality		77	0
<b>Mechanical Stress</b> (Note 2)					
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality		77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data

## Attachment #1

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except $V_{PS1}$ 3/	All $V_{PS1}$ pins
2.	All input and output pins	All other input-output pins

1/ Table II is restated in narrative form in 3.4 below.

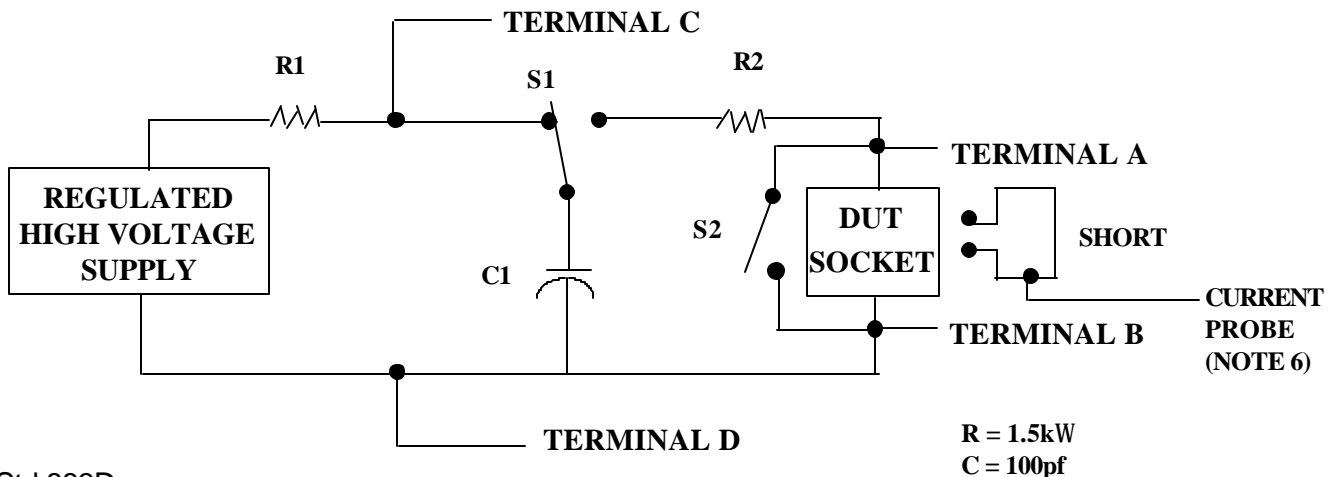
2/ No connects are not to be tested.

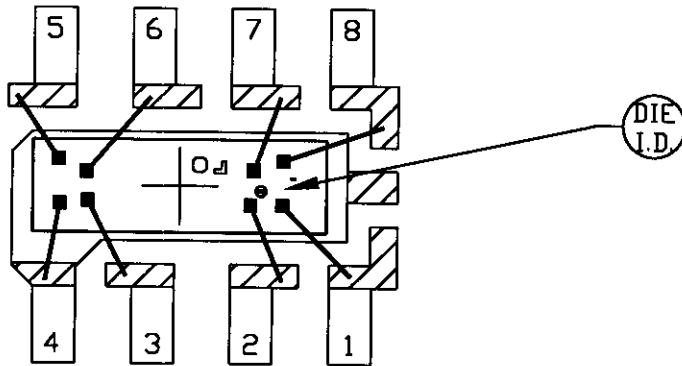
3/ Repeat pin combination I for each named Power supply and for ground

(e.g., where  $V_{PS1}$  is  $V_{DD}$ ,  $V_{CC}$ ,  $V_{SS}$ ,  $V_{BB}$ , GND,  $+V_S$ ,  $-V_S$ ,  $V_{REF}$ , etc).

### 3.4 Pin combinations to be tested.

- a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.
- b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g.,  $V_{SS1}$ , or  $V_{SS2}$  or  $V_{SS3}$  or  $V_{CC1}$ , or  $V_{CC2}$ ) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.
- c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.





USE NON-CONDUCTIVE EPOXY

NOTE: CAVITY DOWN

 BONDABLE AREA

PKG. CODE: K8-5	
CAV./PAD SIZE: 88x28	PKG. DESIGN

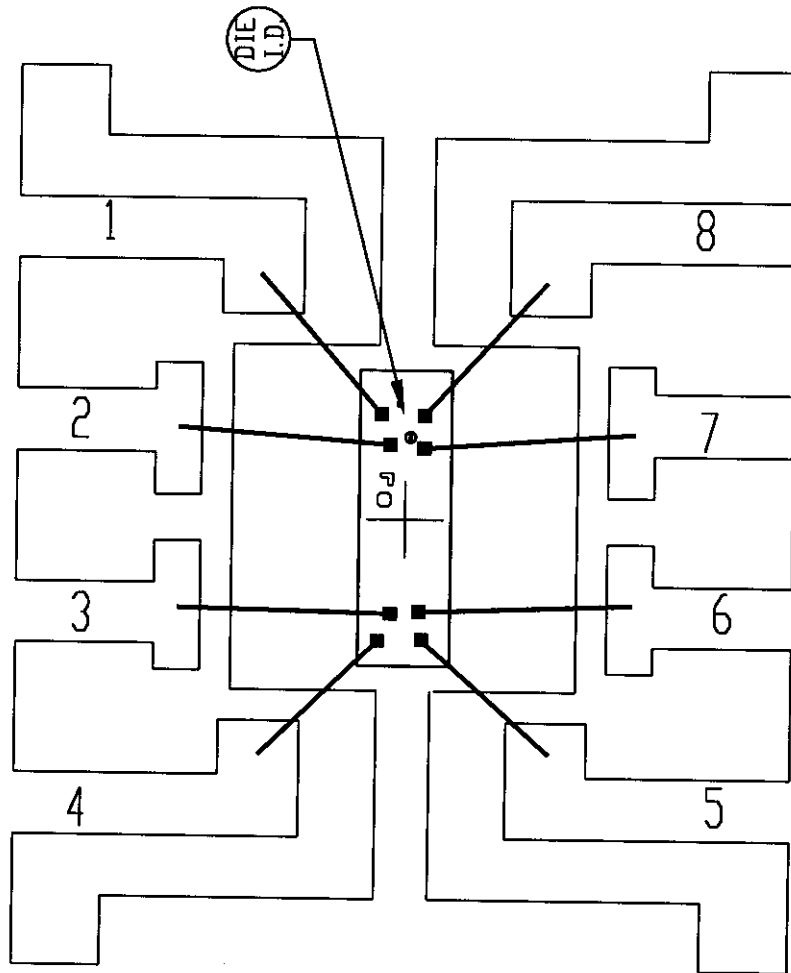
SIGNATURES

DATE

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BOND DIAGRAM #:  
05-1501-0227

REV:  
A



PKG. CODE: S8-2	
CAV./PAD SIZE: 90 X 90	PKG. DESIGN

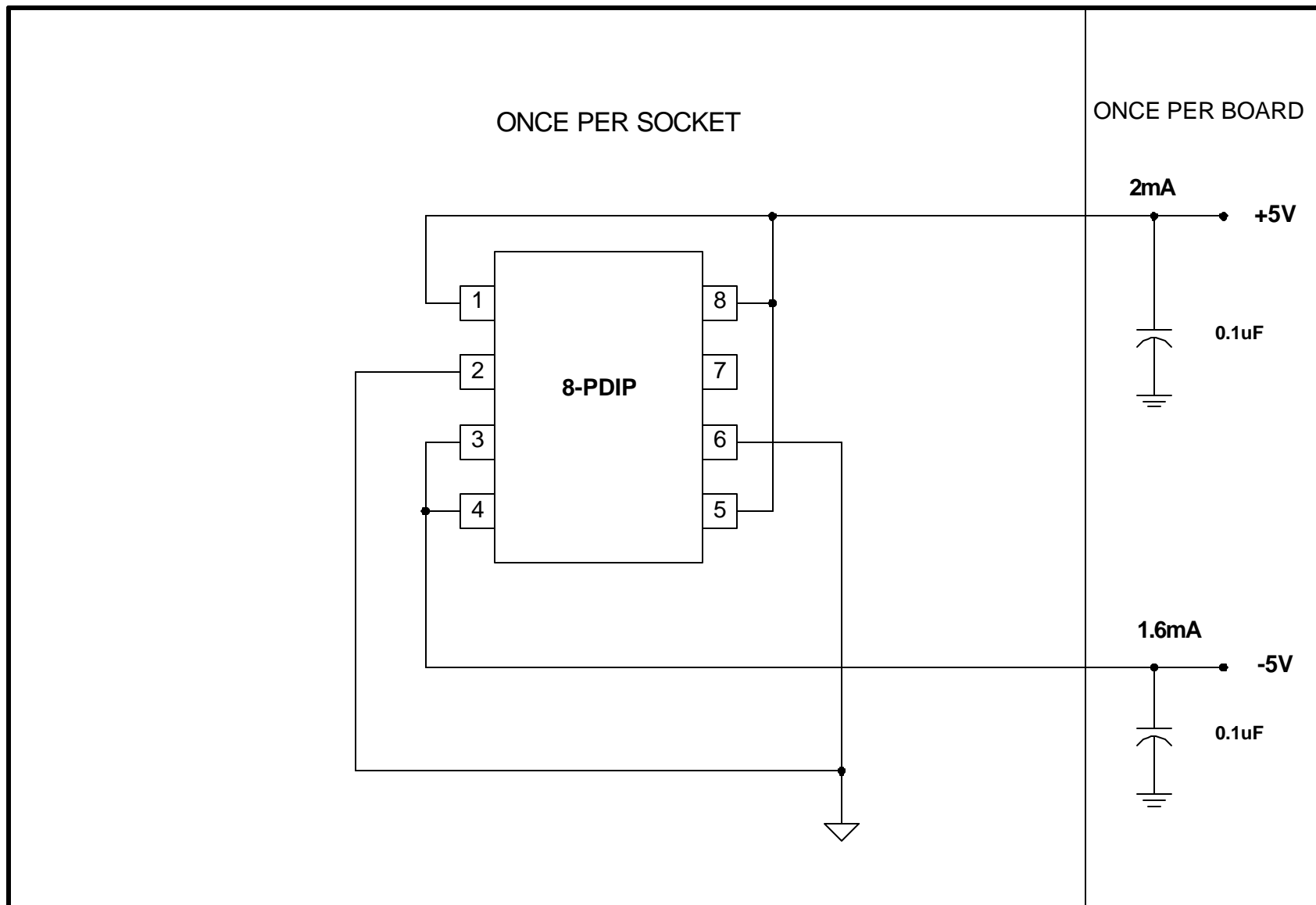
SIGNATURES

DATE

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BOND DIAGRAM #: 05-1501-0228	REV: A
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DEVICES: MAX 903

DRAWN BY: HAK TAN

MAX. EXPECTED CURRENT = 1.6 mA ( -5V ) 2 mA ( +5V )

NOTES: